



Title of Change:	PT3MV products wafer source transfer from Bucheon (Korea) to Mountain Top (US) and manufacturing BOM changed accordingly for SOT23 Parts assembled in Leshan, China.	
Proposed First Ship date:	24 February 2020	
Contact Information:	Contact your local ON Semiconductor Sales Office or <York.Yu@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>	
Change Part Identification:	Affected products will be identified with date code WW10,2020 or newer	
Change Category:	<input checked="" type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON ISMF, Malaysia ON Seremban, Malaysia ON Leshan, China ON Mountain Top, PA	External Foundry/Subcon Sites: None
Description and Purpose:		
ON Semiconductor is notifying customers of wafer source transferring from Bucheon (Korea) to Mountain Top (US) for its PT3MV SOT23 Products assembled in Leshan, China. Differences are as below:		
	Before	After
FAB	Bucheon, Korea, without passivation on die	Mountain Top, US, with passivation on die
Wafer size	6 inch	8 inch
Back grind/ back metal site	Bucheon, Korea	ISMF, Seremban, Malaysia
Back metal composition	67KA TiNiAgSn	12KA Sintered Au
Probe test site	Bucheon, Korea	MYD, Seremban, Malaysia
Lead Frame	Silver Plated lead frame	Copper Plater lead frame
Mold Compound	Sumitomo G600FB	Hysol GR640HV
Purpose of the change: Resolve wafer capacity constrain and follow assembly standard BOM.		

**Qualification Plan:**QV DEVICE NAME BSS123L

RMS: TBD

PACKAGE: SOT23

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1000 hrs
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1000 hrs
HTSL	JESD22-A103	Ta=150°C	1000 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 5 sec	

Estimated date for qualification completion: 31 October 2019

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
BSS123L	BSS123L
BSS138L	BSS123L
2N7002L	BSS123L